



## High-Speed USB2.0 1:2 Multiplexer/DeMultiplexer Switch with Signal Enable

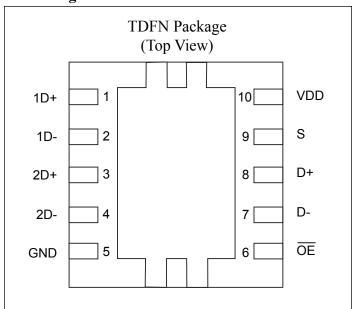
### **Features**

- V<sub>DD</sub> Operation at 2.5 V and 3.3 V
- V<sub>I/O</sub> Accepts Signals up to 5.5 V
- 1.8-V Compatible Control-Pin Inputs
- Low-Power Mode When  $\overline{OE}$  Is Disabled (2  $\mu$ A)
- $r_{ON} = 6\Omega$  Maximum
- $\Delta r_{ON} = 0.2\Omega$  Typical
- Cio(on) = 6 pF Maximum
- Low Power Consumption (50 μA Maximum)
- ESD > 8kV contact on USB signal path per IEC61000-4-2)
- High Bandwidth (1.1 GHz Typical)
- Packaging (Pb-free & Green):
  - 10-contact, TDFN (ZE10)

## **Applications**

- Routes Signals for USB 1.0, 1.1, and 2.0
- · Mobile Industry Processor Interface (MIPI) Signal Routing

## **Pin Configuration**



### **Description**

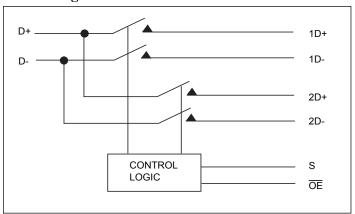
The PI3USB221 is a high-bandwidth switch specially designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os. The wide bandwidth (1.1 GHz) of this switch allows signals to pass with minimum edge and phase distortion. The device multiplexes differential outputs from a USB host device to one of two corresponding outputs. The switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. It is designed for low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480 Mbps).

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## **Block Diagram**



## **Pin Description**

Name	Description
ŌE	Active LOW, Output enable
S	Select input
D	COM port
nD	I/O for USB data path (port 1 and port 2)

## **Truth Table**

S	ŌĒ	Function
X	Н	Disconnect
L	L	D = 1D
Н	L	D = 2D

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## ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

Over operating free-air temperature range (unless otherwise noted)

F B
V <sub>DD</sub> Supply Voltage Range –0.5V to 4.6V
V <sub>IN</sub> Control Input Voltage Range <sup>2, 3</sup>
V <sub>I/O</sub> Switch I/O Voltage Range <sup>2, 3, 4</sup> 0.5V to 7V
$I_{IK} \ Control \ Input \ Clamp \ Current \ (V_{IN} < 0)50 mA$
$I_{I/OK} \ I/O \ Port \ Clamp \ Current \ (V_{I/O} < 0)50 mA$
I <sub>I/O</sub> ON-state Switch Current <sup>5</sup> ±120mA
Continuous current through $V_{DD}$ or $GND$ $\pm 100 mA$
θ <sub>JA</sub> Package Thermal Impedance
TLLGA Package48.7°C/W
TDFN Package
T <sub>stg</sub> Storage temperature range65 to 150°C

#### Notes

- 1. Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. All voltages are with respect to ground, unless otherwise specified.
- 3. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 4. VI and VO are used to denote specific conditions for VI/O.
- 5. II and IO are used to denote specific conditions for II/O.
- 6. The package thermal impedance is calculated in accordance with JESD 51-7.

## Recommended Operating Conditions<sup>1</sup>

Symbol	Description	Parameter	Min.	Max.	Unit
$V_{ m DD}$	Supply voltage		2.3	3.6	
TT' 1 1	High level control input voltage	$V_{DD} = 2.3 \text{ V to } 2.7 \text{ V}$	1.4	-	V
$V_{IH}$	High-level control input voltage	$V_{DD} = 2.7 \text{ V to } 3.6 \text{ V}$	1.3	-	
		$V_{DD} = 2.3 \text{ V to } 2.7 \text{ V}$		0.6	·
$V_{\rm IL}$	Low-level control input voltage	$V_{DD} = 2.7 \text{ V to } 3.6 \text{ V}$		0.6	
V <sub>I/O</sub>	Data input/output voltage		0	5.5	
TA	Operating free-air temperature		-40	85	°C

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#### Note:

1. All unused control inputs of the device must be held at  $V_{\mathrm{DD}}$  or GND to ensure proper device operation.





### **ELECTRICAL CHARACTERISTICS**

Over operating free-air temperature range (unless otherwise noted)

Parameter		<b>Testing Conditions</b>		Min.	Тур.	Max.	Unit	
V <sub>IK</sub>		$V_{DD} = 3.6V, 2.7V, I_I = -18 \text{ mA}$				-1.8	V	
I <sub>IN</sub>	Control Inputs	$V_{DD} = 3.6V, 2.7V, 0V, V_{IN} = 0V \text{ to } 3.6V$				±1		
$I_{OZ}^3$		$V_{DD} = 3.6V, 2.7V, V_{IN} = V_{DD} \text{ or } GN$ $V_{O} = 0V \text{ to } 3.6V, V_{I} = 0V, \text{ Switch } O$				±1		
Lorm		$V_{DD} = 0V$	$V_{I/O} = 0V \text{ to } 3.6V$			±2		
$I_{(OFF)}$		v DD - 0 v	$V_{I/O} = 0$ to 2.7V			±1		
$I_{CC}$		$V_{DD}$ = 3.6V, 2.7V, $V_{IN}$ = $V_{DD}$ or GN $I_{I/O}$ = 0 V, Switch ON or OFF	ND,			50	μΑ	
I <sub>CC</sub> (low power mode)		$V_{DD} = 3.6V, 2.7V, V_{IN} = V_{DD}$ or GND, Switch disabled, ( $\overline{OE}$ in high state)				2		
DI 4	Control	Control		$V_{DD} = 2.7V$ , S sweeps from 1.4V to 3.3V, OE/ = 0V			15	
DI <sub>CC</sub> <sup>4</sup> Control Inputs			$V_{\rm DD}$ = 2.7V, OE/ sweeps from 1.4V to 3.3V, S = 0V			0.75		
C <sub>IN</sub>	Control Inputs	$V_{DD} = 3.3V$ , 2.5V, $V_{IN} = 3.3V$ or 0V			1	2		
C <sub>io(OFF)</sub>		$V_{\rm DD} = 3.3 \text{V}, 2.5 \text{V}, V_{\rm IN} = 3.3 \text{V} \text{ or } 0 \text{V}, \text{ Switch OFF}$			2	4	pF	
C <sub>io(ON)</sub>		$V_{DD} = 3.3V$ , 2.5V, $V_{IN} = 3.3V$ or 0V, Switch ON			5	6		
$r_{ON}^{5}$		$V_{DD} = 3V, 2.3V$	$V_I = 0V, I_O = 30 \text{ mA}$			6		
ION		$V_{DD} = 3V$ , 2.3V	$V_I = 2.4V$ , $I_O = -15 \text{ mA}$			6		
Dron		$V_{DD} = 3V, 2.3V$	$V_I = 0V, I_O = 30 \text{ mA}$		0.2		Ω	
DION			$V_I = 1.7V$ , $I_O = -15 \text{ mA}$		0.2		32	
TON/A-1		$V_{DD} = 3V, 2.3V$	$V_I = 0V, I_O = 30 \text{ mA}$		1			
r <sub>ON</sub> (flat)		עט אין	$V_I = 1.7V$ , $I_O = -15 \text{ mA}$		1			

#### Notes:

- 1.  $\,V_{IN}$  and  $I_{IN}$  refer to control inputs. VI, VO, II, and IO refer to data pins.
- 2. All typical values are at  $V_{DD} = 3.3 \text{ V}$  (unless otherwise noted),  $T_A = 25^{\circ}\text{C}$ .
- 3. For I/O ports, the parameter IOZ includes the input leakage current.
- 4. This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{DD}$  or GND.
- 5. Measured by the voltage drop between the input and output terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two terminals.

### DYNAMIC ELECTRICAL CHARACTERISTICS

over operating range,  $T_A = -40$ °C to 85°C,  $V_{DD} = 3.3 \text{ V} \pm 10$ %, GND = 0 V

Symbol	Parameter	<b>Test Conditions</b>	Typ. <sup>(1)</sup>	Unit
X <sub>TALK</sub>	Crosstalk	$R_L = 50\Omega, f = 250 \text{ MHz}$	-40	dD
O <sub>IRR</sub>	OFF isolation	$R_L = 50\Omega, f = 250 \text{ MHz}$	<b>-4</b> 1	dB
BW	Bandwidth (-3 dB)	$R_L = 50\Omega$	1.1	GHz

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#### Note:

1. For Max or Min conditions, use the appropriate value specified under Electrical Characteristics for the applicable device type.





## **SWITCHING CHARACTERISTICS** over operating range, $T_A = -40$ °C to 85°C, $V_{DD} = 3.3 \text{ V} \pm 10\%$ , GND = 0V

Symbol	Parameter		Min.	Typ.(1)	Max.	Unit
t <sub>pd</sub>	Propagation Delay <sup>2,3</sup>			0.25		
t <sub>ON</sub> Line enable time	S to D, nD			125		
	Line enable time	OE to D, nD			100	
t <sub>OFF</sub> Line disab	Line disable time $\frac{S \text{ to D, nD}}{\overline{OE} \text{ to D, nD}}$	S to D, nD			12	ns
				12	115	
t <sub>SK(O)</sub>	Output skew between center port to any other port <sup>2</sup>			0.1	0.2	
t <sub>SK(P)</sub>	Skew between opposite transitions of the same output $(tPHL - tPLH)^2$			0.1	0.2	

#### Notes:

- 1. For Max or Min conditions, use the appropriate value specified under Electrical Characteristics for the applicable device type.
- Specified by design
- 3. The switch contributes no propagational delay other than the RC delay of the on resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 10-pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch, when used in a system, is determined by the driving circuit on the driving side of the switch and its interactions with the load on the driven side.





**Application Information** 

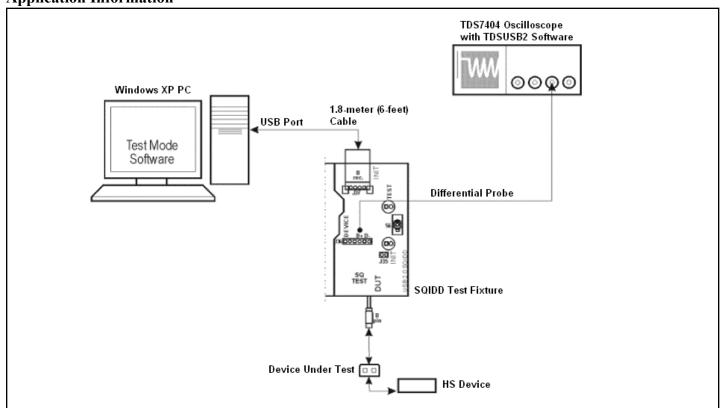
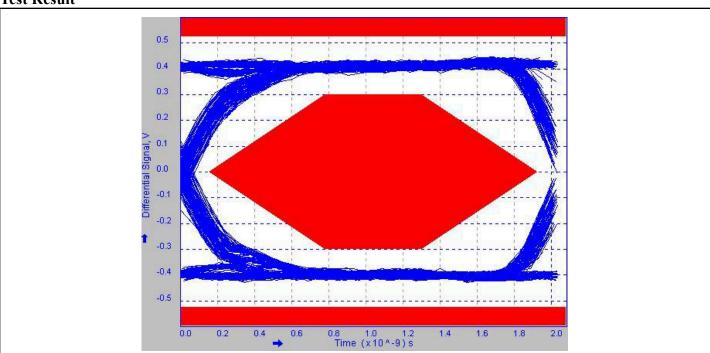


Figure 1: HS Eye Test Setup

## **Test Result**

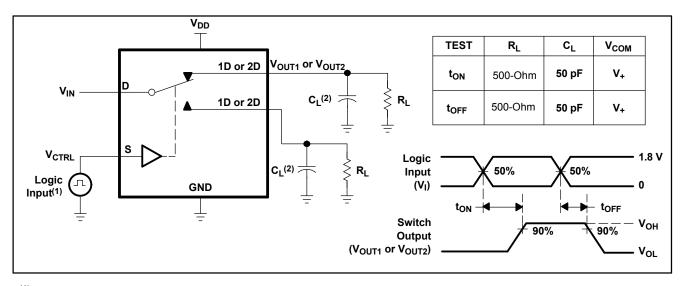


Test Result 1: High-speed, Up-stream, Near-end Eye of PI3USB221



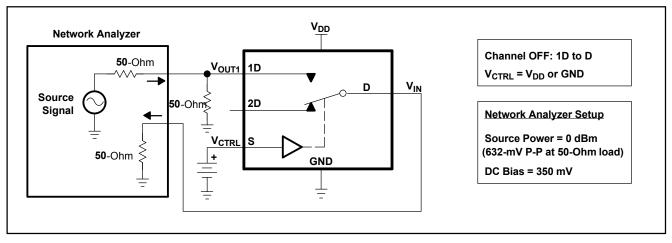


### **Parameter Measurement Information**



- (1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50-Ohm, t<sub>f</sub> < 5 ns, t<sub>f</sub> < 5 ns.
- (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 2. Turn-On (t<sub>ON</sub>) and Turn-Off Time (t<sub>OFF</sub>)



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Figure 3.OFF Isolation (O<sub>ISO</sub>)



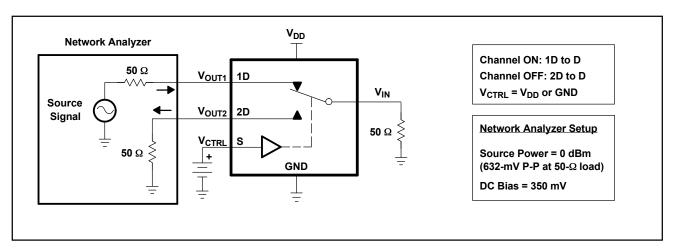


Figure 4. Crosstalk (X<sub>TALK</sub>)

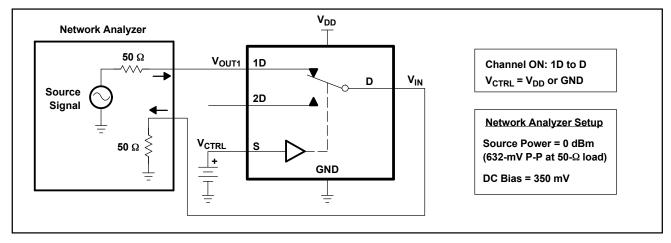


Figure 5. Bandwidth (BW)

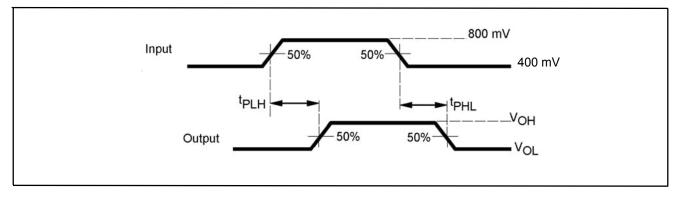


Figure 6. Propagation Delay





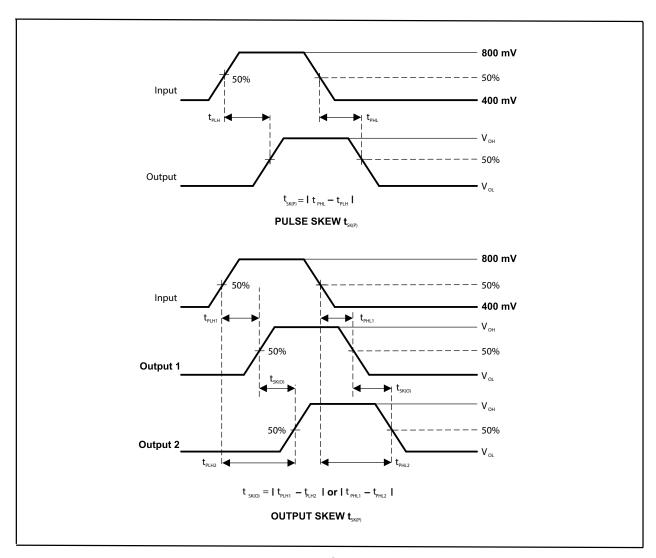


Figure 7. Skew Test

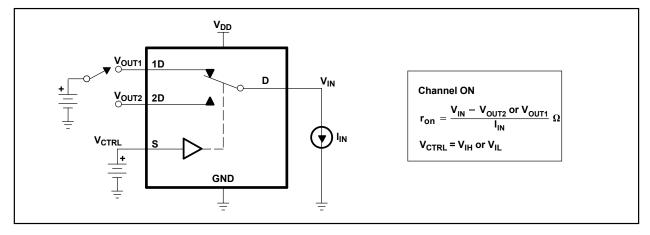


Figure 8. ON-State Resistance (ron)





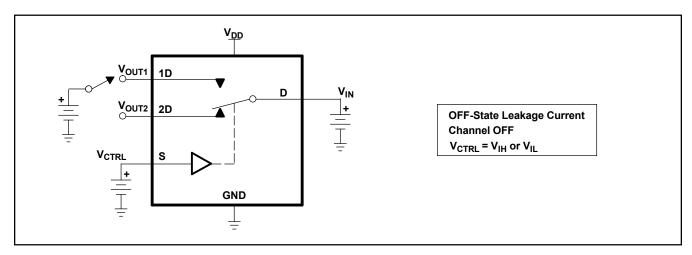


Figure 9. OFF-State Leakage Current

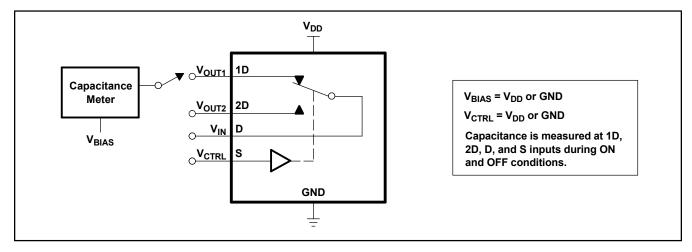
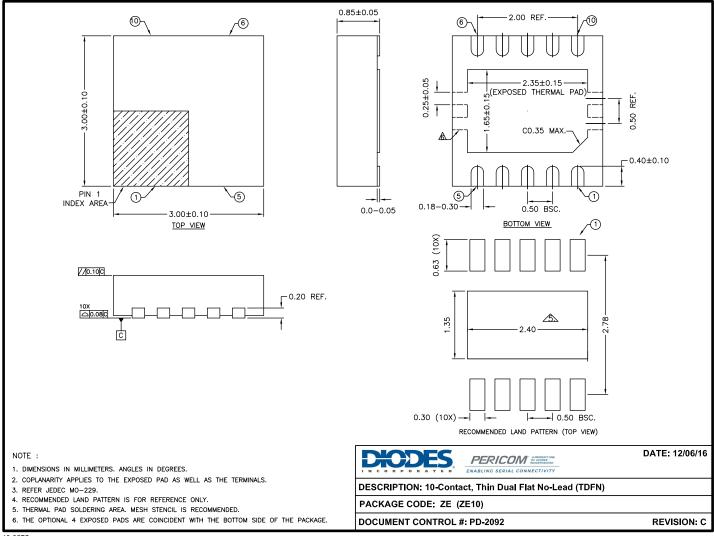


Figure 10. Capacitance





## **Packaging Mechanical: 10-Contact TDFN**



16-0275

Note: For latest package info, please check: http://www.pericom.com/support/packaging/packaging-mechanicals-and-thermal-characteristics/

# **Ordering Information**<sup>(1-3)</sup>

Ordering Code	Package Code	Package Description
PI3USB221ZEEX	ZE	10-Contact, Thin Dual Flat No Lead (TDFN), Tape & Reel

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#### Notes

- 1. Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
- 2. E = Pb-free and Green
- 3. Adding an X suffix = Tape/Reel





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